



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP FF 12900 4-p 100GbE CFP EC Mod(JG858A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2 #

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on top crashworthy bridge 2, and then remove the top crashworthy bridge 2 from panel 8.
2. Unscrew the screws on heat sink 6, and then remove heat sink 6 from panel 8.
3. Unscrew the screws on front panel 9, and then remove the front panel 9 from panel 8.
4. Unscrew the screws on pcb 1, and then remove pcb 1.
5. Unscrew the screws on guiding set 7, and then remove guiding set 7 from pcb 1.
6. Unscrew the screws on pcb 5, and then remove pcb 5.
7. Remove shielding finger 3 from front panel 9.
8. Remove film 4 from front panel 9.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

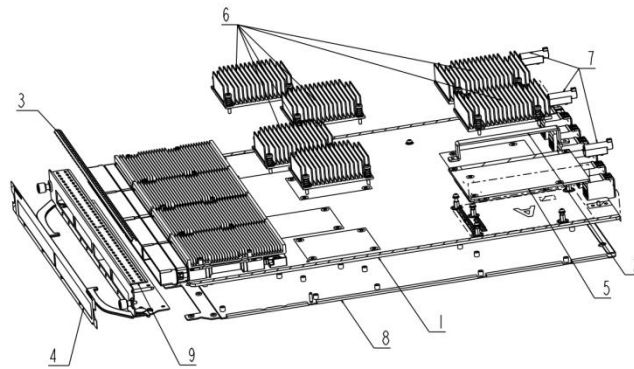


Figure 1 disassembly process

3.3 Material of the facility built

Table 1

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	1	Complex PWB	3949.6	57.158%	The surface If PCB is greater than 10 square centimeters	
	2	Fe	26	0.376%		Fe recycling
	3	Be-Cu	1.7	0.025%		Cu recycling
	4	PC	1.5	0.022%		Pla recycling
	5	Complex PWB	60	0.868%	The surface If PCB is greater than 10 square centimeters	
	6	Al	820.2	11.87%		Al recycling
	7	Zn	48.0	0.695%		Zn recycling
	8	Fe	1675	24.24%		Fe recycling
	9	Fe	328	4.747%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.09.11	V0	Feng Junnan	Initial version